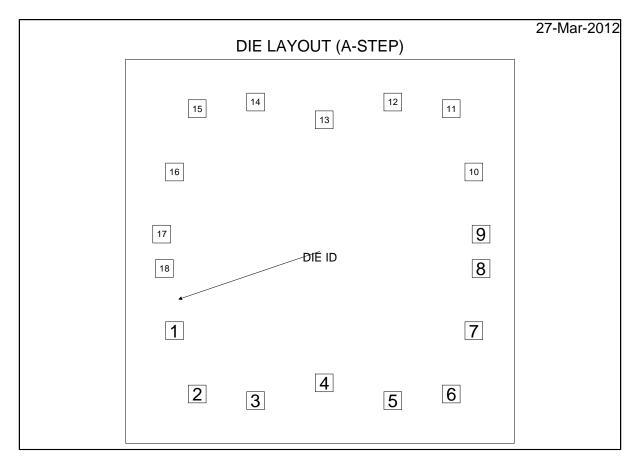


DS26LV32-MD8 WLTR MCD5080A 3V Enhanced CMOS Quad Differential Line Receiver



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information				
Physical Die	DS26LV32	Bond Pad Opening	91.70µm x 91.70µm			
Identification		Size (min)				
Die Step	A	Bond Pad Metalization	AL 0.5%CU			
Physical Attributes		Passivation	PECVDOX NITRIDE			
Wafer Diameter	152.4mm	Back Side Metal	Bareback			
Die Size (Drawn)	2006.60µm x 1981.20µm	Back Side Connection	GND			
	79.0mils x 78.0mils					
Thickness	304.8µm Nominal					
Min Pitch	177.80µm					
Note: All values are rounded to the nearest micron.						
Special Assembly Requirements:						



DS26LV32-MD8 WLTR MCD5080A

3V Enhanced CMOS Quad Differential Line Receiver

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Х	Y	Х		Y
RI 1-	1	-751	-410	92	х	9
RI 1+	2	-634	-736	92	х	92
RO 1	3	-333	-771	92	х	92
EN	4	22	-679	92	х	92
RO 2	5	376	-771	92	х	92
RI 2+	6	677	-736	92	х	92
RI 2-	7	794	-410	92	х	9
GND	8	831	-89	92	х	92
GND	9	831	89	92	х	92
RI 3-	10	794	410	92	х	92
RI 3+	11	677	736	92	х	92
RO 3	12	376	771	92	х	92
EN*	13	22	679	92	х	92
RO 4	14	-333	771	92	х	92
RI 4+	15	-634	736	92	х	92
RI 4-	16	-751	410	92	х	92
Vcc	17	-817	89	92	х	92
Vcc	18	-803	-89	92	х	92



DS26LV32-MD8 WLTR MCD5080A 3V Enhanced CMOS Quad Differential Line Receiver

Notes						
THE CONTENTS OF THIS DOCUMENT ARE PROVIDED IN CONNECTION WITH NATIONAL SEMICONDUCTOR CORPORATION ("NATIONAL") PRODUCTS. NATIONAL MAKES NO REPRESENTATIONS OR WARRANTIES WITH RESPECT TO THE ACCURACY OR COMPLETENESS OF THE CONTENTS OF THIS PUBLICATION AND RESERVES THE RIGHT TO MAKE CHANGES TO SPECIFICATIONS AND PRODUCT DESCRIPTIONS AT ANY TIME WITHOUT NOTICE. NO LICENSE, WHETHER EXPRESS, IMPLIED, ARISING BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT.						
TESTING AND OTHER QUALITY CONTROLS ARE USED TO THE EXTENT NATIONAL DEEMS NECESSARY TO SUPPORT NATIONAL'S PRODUCT WARRANTY. EXCEPT WHERE MANDATED BY GOVERNMENT REQUIREMENTS, TESTING OF ALL PARAMETERS OF EACH PRODUCT IS NOT NECESSARILY PERFORMED. NATIONAL ASSUMES NO LIABILITY FOR APPLICATIONS ASSISTANCE OR BUYER PRODUCT DESIGN. BUYERS ARE RESPONSIBLE FOR THEIR PRODUCTS AND APPLICATIONS USING NATIONAL COMPONENTS. PRIOR TO USING OR DISTRIBUTING ANY PRODUCTS THAT INCLUDE NATIONAL COMPONENTS, BUYERS SHOULD PROVIDE ADEQUATE DESIGN, TESTING AND OPERATING SAFEGUARDS.						
EXCEPT AS PROVIDED IN NATIONAL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, NATIONAL ASSUMES NO LIABILITY WHATSOEVER, AND NATIONAL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY RELATING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR INTRALED AND THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR INTRALED AND THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR INTRALED AND THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING TO THE PROPERTY REAL AND THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING THE PROPERTY OR OTHER INTELLED AND THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING THE PROPERTY OR OTHER INTELLED AND THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING THE PROPERTY OR OTHER INTELLED AND THE PROPERTY REAL AND THE PR						
LIFE SUPPORT POLICY						
NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS PRIOR WRITTEN APPROVAL OF THE CHIEF EXECUTIVE OFFICER AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION.						
As used herein: Life support devices or systems are devices which (a) are intended for surgical implant into the body, or (b) support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in a significant injury to the user. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system or to affect its safety or effectiveness.						
National Semiconductor and the National Semiconductor logo are registered trademarks of National Semiconductor Corporation. All other brand or product names may be trademarks or registered trademarks of their respective holders.						
Copyright© 2007 National Semiconductor Corporation						
For the most current product information visit us at www.national.com						
IN U.S.A. IN EUROPE IN ASIA PACIFIC IN JAPAN Tel: 1 800 962 0673 / 18760 Tel: 49 (0) 8141 35 1370 Tel: (852) 2737 1826 Tel: 81 3 5639 7560 Fax: 1 207 541 6140 Fax: 49 (0) 8141 35 1666 Tel: 81 3 5639 7560 Tel: 81 3 5639 7560						

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		Applications			
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive		
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications		
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers		
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps		
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy		
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial		
Interface	interface.ti.com	Medical	www.ti.com/medical		
Logic	logic.ti.com	Security	www.ti.com/security		
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense		
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video		
RFID	www.ti-rfid.com				
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com		
Wireless Connectivity	www.ti.com/wirelessconnectivity				

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2012, Texas Instruments Incorporated